

**AN ELECTRICAL CIRCUIT ASSEMBLY WITH MICRO-SOCKET****Abstract of the Invention**

5       An assembly of the present invention has an integrated circuit device electrically and mechanically connected to the substrate. At least one electrically conductive connecting element is on one of the substrate and circuit device and at least one socket is on the other of the substrate and circuit device. The socket receives the at least one connecting element and comprises at least two resilient members. The resilient members are biased against the connecting element so that the circuit device and the substrate are held in electrical and mechanical connection by the biasing force of the resilient members against the connecting element.